

[illegible]

- a first step of applying an organosilane solution as

a non-slip agent onto at least one of both surfaces of said hub and said inertia mass body, both surfaces facing the polymer elastic body;

a second step of press-fitting the polymer elastic body applied onto the organosilane solution between the hub and the inertia mass body; and

a third step of heating the damper to remove a solvent thereof, reacting the organosilane in the surface of said polymer elastic body and at least one of both surface of said hub and said inertia mass body, and attaching and fitting said hub and said inertia mass body.

5. A process of a damper being a fitting type including a hub, a inertia mass body, and a polymer elastic body such a rubber press-fitted between the hub and the inertia mass body from an axis direction thereof, the process comprising:

a first step of applying an organosilane solution as a non-slip agent onto at least one of both surfaces of said hub and said inertia mass body, said both surfaces being faced by respective surfaces of said polymer elastic body;

a second step of press-fitting said polymer elastic body between said hub and said inertia mass body after said first step; and

a third step of heating the damper to remove a solvent thereof, reacting the organosilane in the surface of said polymer elastic body and at least one of both surface of said hub and said inertia mass body, and attaching and fitting said hub and said inertia mass body.

6. The process of a damper according to one of claims 4 and 5, wherein at least one of both surfaces of said hub and said inertia mass body being attached and fitted to said organosilane, said both surfaces facing said polymer elastic body is without performing heat surface treatment.

7. The process of a damper according to any one of claims 4 and 6, wherein surface roughness in at least of one of a metal surface adhering to the polymer elastic body in said hub and a metal surface adhering to the polymer elastic body in said inertia mass body is within a range of 5 to 50 μmRz (JIS B0601).